Panasonic CONNECT



Windows 11 Pro Fully Rugged Laptop with 14.0" Outdoor Display and Modular Expansion Areas...

TOUGHBOOK 40 mk2

The 14.0” fully-rugged Panasonic TOUGHBOOK 40 laptop breaks new ground offering unrivaled flexibility in even the most demanding and unpredictable environments, including Defence, Mining and Utilities. It has a modular design that allows mobile workers to modify the device quickly and easily for different challenges by equipping 8 expansion areas. The powerful rugged laptop is built for use in the most extreme conditions and designed for field specialists, incorporating quick release self-encrypting secure drives and providing up to 36-hours of battery life to support mission critical operations.

Key Features

The 14” fully-rugged Panasonic TOUGHBOOK® 40 offers unrivaled flexibility in even the most demanding and unpredictable environments with its class-leading eight modular areas including its innovative modular expansion packs (xPAK’s). Optical drives, authe

Windows 11 Pro

Intel® Core™ Ultra5 135H Processor (with Intel vPro® Technology) / Intel® Core™ Ultra7 165H (with Intel vPro® Technology) Processor optional

Up to 180cm drop resistance***, IP66 water and dust resistance, MIL-STD 810H certified***

Long battery life of up to 18 hours (up to 36 hours with optional 2nd battery*)

intel CORE ULTRA 7

intel CORE ULTRA 5

Panasonic CONNECT

TOUGHBOOK 40 mk2

https://ap.connect.panasonic.com/my/en/toughbook-40-mk2

Model	TOUGHBOOK 40mk2, 16GB RAM,512GB SSD, 1 x standard battery pack
OS (Operating System)	Windows 11 Pro
CPU (Mobile Computing Platform) -> Processor	Intel® Core™ Ultra5 vPro™ Processor (optional Intel® Core™ Ultra7 vPro™*)
CPU (Mobile Computing Platform) -> Graphics chips	Intel® Graphics, supports Intel® ArcTM Graphics when 2 RAM Modules installed
Memory (RAM) (RAM Standard / Maximum) (Main memory)	Built-in 16GB RAM (max 64GB RAM*)
Storage	Quick release 512GB NVMe OPAL SSD (with heater)
Display & Graphics	14.0" Active Matrix (TFT) colour LCD 1920 x 1080 (FHD) LCD with sunlight-viewable glove-enabled touchscreen (up to 1,200cd/m² brightness)
Wireless	Mobile Broadband:4G LTE, GPS:U-Blox NEO-M9N, Wi-Fi:Intel® Wi-Fi7 BE200, Bluetooth:5.1 Class 1
I/O Ports (Interface)	USB 3.2:x2 (Gen 1 Type-A), Micro SDXC Memory Card:x1, Thunderbolt 4:x1 HDMI:x1, LAN:IEEE 802.3 10Base-T / IEEE 802.3u 100BASE-TX / IEEE 802.3ab 1000BASE-T (optional 2nd GLAN*), Quad Path Through Connector:x1
Left expansion area	2nd SSD, Smart Card Reader, DVD Multi Drive, Blu Ray Drive,
Right expansion area	2nd Battery, Smart Card Reader
Palmrest expansion area	Fingerprint reader (Windows Hello, Multi-user authentication)Contactless Smart Card Reader
Rear expansion area	VGA + True Serial (RS232) + 2nd native GLAN, USB 3.1 Type A + True Serial (RS232) + 2nd HDMI, USB 3.1 Type A + USB Type-C + 2nd HDMI
Camera -> Front	5MP with IR / privacy shutter (Windows Hello compliant) optional*
Audio (Sound)	Waves MaxxAudio® Stereo Speakers, 4 integrated microphones, Headset:x1
Security	TPM 2.0, Password security, Integrated hardware security lock slot
Dimensions -> Main Unit	354mm x 301mm x 54.4mm (without protruding parts)
Weight -> Main Unit	Approx 3.37kg (depending on configuration)
Battery -> Battery Life	Standard: approx 12 hours (Mobile Mark™ 25)With optional 2nd battery: approx 24 hours (Mobile Mark™ 25)*
Power (Power supply) -> AC adapter	Input: 100V - 240V AC, 50Hz/ 60Hz, Output: 15.6V DC, 7.05A, DC In:x1
Power (Power supply) -> Battery (Battery pack)	Lithium-Ion 10.8V, 6500mAh (typical), 6300mAh (minimum)
Power (Power supply) -> Hot Swap	Standby function, ACPI BIOS
Durability -> Drop resistance	MIL-STD810H, 180cm***
Durability -> Dust resistance	IP6x
Durability -> Water resistance	IPx6
Operating temperature	MIL-STD810H, -29°C to +63°C***
Included in Box	Power Supply, Power Cord, Capacitive Stylus Pen, Display Cleaning Cloth and User Manual
Integrated Options	Port Replicator:x1,
Electromagnetic Compatibility (EMC)	MIL-STD461G*
Footnote Description	*Optional**One option exclusive possible in configuration port / business expansion module***Tested by an independent third party lab following MIL-STD810H Method 516.8 Procedure IV for transit drop test and Method 501.7 and 502.7 Procedure I for operation temperature test. May differ depending on models and options